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Dated: October 12, 2005

Signature:

Richard H. Anderson
(Richard H. Anderson)

Docket No.: 29936/39889
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Sang K. Park

Application No.: 10/749,022

Confirmation No.: 9225

Filed: December 30, 2003

Art Unit: 2812

For: METHOD OF FORMING COPPER WIRING IN
SEMICONDUCTOR DEVICE

Examiner: L. A. Gurley

AMENDMENT IN RESPONSE TO NON-FINAL OFFICE ACTION

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

INTRODUCTORY COMMENTS

In response to the Office Action dated July 13, 2005, please amend the above-identified U.S. patent application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 7 of this paper.